## 捷多邦,专业PC**SN54ABT46833** (SNIE4ABT16833 DUAL 8-BIT TO 9-BIT PARITY BUS TRANSCEIVERS

SCBS097D - FEBRUARY 1991 - REVISED JANUARY 1997

- Members of the Texas Instruments
  Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes
  PCB Layout
- High-Drive Outputs (–32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Parity-Error Flag With Parity Generator/Checker
- Register for Storage of Parity-Error Flag
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

#### description

The 'ABT16833 consist of two noninverting 8-bit to 9-bit parity bus transceivers and are designed for communication between data buses. For each transceiver, when data is transmitted from the A bus to the B bus, an odd-parity bit is generated and output on the parity I/O pin (1PARITY or 2PARITY). When data is transmitted from the B bus to the A bus, 1PARITY (or 2PARITY) is configured as an input and combined with the B-input data to generate an active-low error flag if odd parity is not detected.

SN54ABT16833 . . . WD PACKAGE SN74ABT16833 . . . DGG OR DL PACKAGE (TOP VIEW)

			- W/N
1OEB	1		] 10EA
1CLK	2		] 1CLR
1ERR	3	54	] 1PARITY
GND [	4	53	] GND
1A1 [	5	52	] 1B1
1A2 [	6	51	] 1B2
V <sub>CC</sub> [	7	50	] v <sub>cc</sub>
1A3 [	8	49	] 1B3
1A4 [	9	48	] 1B4
1A5 [	10	47	] 1B5
GND [	11	46	] GND
1A6 [	12	45	] 1B6
1A7 [	13		] 1B7
1A8 [	14	43	] 1B8
2A1 [	15	42	] 2B1
2A2 [	16	41	] 2B2
2A3 [	17	40	] 2B3
GND [	18	39	] GND
2A4 [	19	38	] 2B4
2A5 [	20	37	] 2B5
2A6 [	21	36	] 2B6
Vcc [	22	35	] V <sub>CC</sub>
2A7 [	23	34	] 2B7
2A8 [	24	33	] 2B8
GND [	25	32	] GND
2ERR	26	31	2PARITY
2CLK	27	30	] 2CLR
2 <mark>OEB</mark> [	28	29	] 2 <mark>0EA</mark>

The error (1ERR or 2ERR) output is configured as an open-collector output. The B-to-A parity-error flag is clocked into 1ERR (or 2ERR) on the low-to-high transition of the clock (1CLK or 2CLK) input. 1ERR (or 2ERR) is cleared (set high) by taking the clear (1CLR or 2CLR) input low.

The output-enable (OEA and OEB) inputs can be used to disable the device so that the buses are effectively isolated. When both OEA and OEB are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



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#### description (continued)

The SN54ABT16833 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16833 is characterized for operation from -40°C to 85°C.

#### **FUNCTION TABLE**

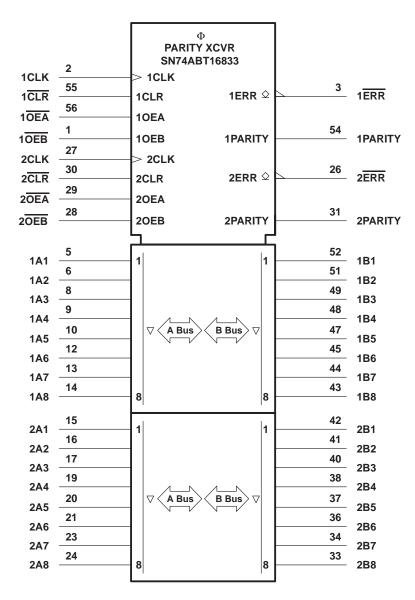
		ı	NPUTS				OUTPU	JT AND I/O		
OEB	OEA	CLR	CLK	Ai Σ OF H	Bi <sup>†</sup> Σ OF H	Α	В	PARITY	ERR‡	FUNCTION
L	Н	Х	Х	Odd Even	NA	NA	Α	L H	NA	A data to B bus and generate parity
Н	L	Н	1	NA	Odd Even	В	NA	NA	H L	B data to A bus and check parity
Х	Х	L	Х	Х	Χ	Χ	NA	NA	Н	Check error-flag register
н	Н	H L H	No↑ No↑ ↑	X X Odd Even	Х	Z	Z	Z	NC H H L	Isolation§
L	L	Х	Х	Odd Even	NA	NA	Α	H L	NA	A data to B bus and generate inverted parity

NA = not applicable, NC = no change, X = don't care

<sup>†</sup> Summation of high-level inputs includes PARITY along with Bi inputs.

<sup>‡</sup> Output states shown assume ERR was previously high. § In this mode, ERR (when clocked) shows inverted parity of the A bus.

## logic symbol†

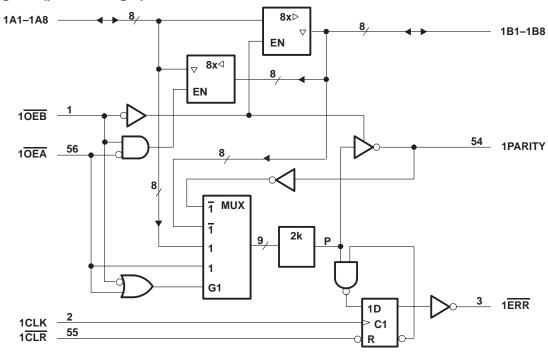


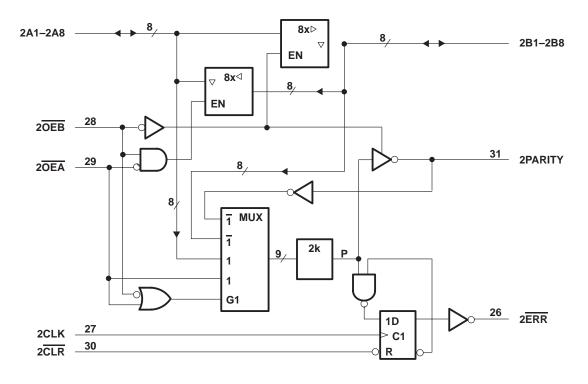
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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#### logic diagram (positive logic)





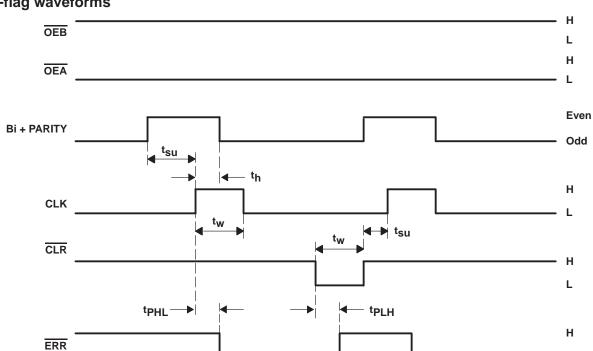
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#### **ERROR-FLAG FUNCTION TABLE**

INP	UTS	INTERNAL TO DEVICE	OUTPUT PRE-STATE	OUTPUT ERR	FUNCTION
CLR	CLK	POINT P	ERR <sub>n-1</sub> †	EKK	
Н	1	Н	Н	Н	
Н	$\uparrow$	X	L	L	Sample
Н	$\uparrow$	L	X	L	
L	Х	Х	X	Н	Clear

<sup>†</sup> State of ERR before changes at CLR, CLK, or point P

## error-flag waveforms



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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	0.5 V to 5.5 V
Current into any output in the low state, Io: SN54ABT16833	96 mA
SN74ABT16833	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	
DL package	74°C/W
Storage temperature range, T <sub>stg</sub>	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 3)

			SN54AB	T16833	SN74AB	Г16833	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	2	2		V
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V	
٧ <sub>I</sub>	Input voltage		0	Vcc	0	Vcc	V
Vон	High-level output voltage	ERR		5.5		5.5	V
lон	High-level output current	Except ERR	3	-24		-32	mA
loL	Low-level output current	•	0	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	DAMETER	TEST COL	IDITIONS	Т	A = 25°C	;	SN54AB	Г16833	SN74AB1	16833	UNIT
	RAMETER	I EST CON	TEST CONDITIONS			MAX	MIN	MAX	MIN	MAX	UNII
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5	3		2.5				
Vон	All outputs	$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3	3.4		3		3		V
VOH	except ERR	V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$				2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*	2.7				2		
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 24 mA		0.25	0.55		0.55			V
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$		0.3	0.55*				0.55	V
$V_{hys}$	_				100			_			mV
IOH	ERR	$V_{CC} = 4.5 \text{ V},$	V <sub>OH</sub> = 5.5 V			20		20		20	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100		J. J		±100	μΑ
ICEX	Outputs high	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 \text{ V}$			50		50		50	μΑ
1.	Control inputs	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND				±1	5	±1		±1	μΑ
Ħ	A or B ports	VCC = 5.5  V,  V = V	CC or GIAD			±100	90	±100		±100	μΑ
IJЦ	A or B ports	$V_{CC} = 0$ ,	$V_I = GND$			<del>-</del> 50	Q Q	<del>-</del> 50		<del>-</del> 50	μΑ
IO <sup>‡</sup>		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
IOZH§		V <sub>CC</sub> =5.5 V,	$V_0 = 2.7 \text{ V}$			50		50		50	μΑ
I <sub>OZL</sub> §		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			<del>-</del> 50		<del>-</del> 50		<del>-</del> 50	μΑ
		V <sub>CC</sub> = 5.5 V,	Outputs high		1.5	2		2		2	
Icc	A or B ports	$I_{O} = 0$ ,	Outputs low		28	36		36		36	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		1	2		2		2	
ΔICC¶		V <sub>CC</sub> = 5.5 V, One ir Other inputs at V <sub>CC</sub>				50		50		50	μΑ
C <sub>i</sub>	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF
C <sub>io</sub>	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			9						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.



<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>§</sup> The parameters IOZH and IOZL include the input leakage current.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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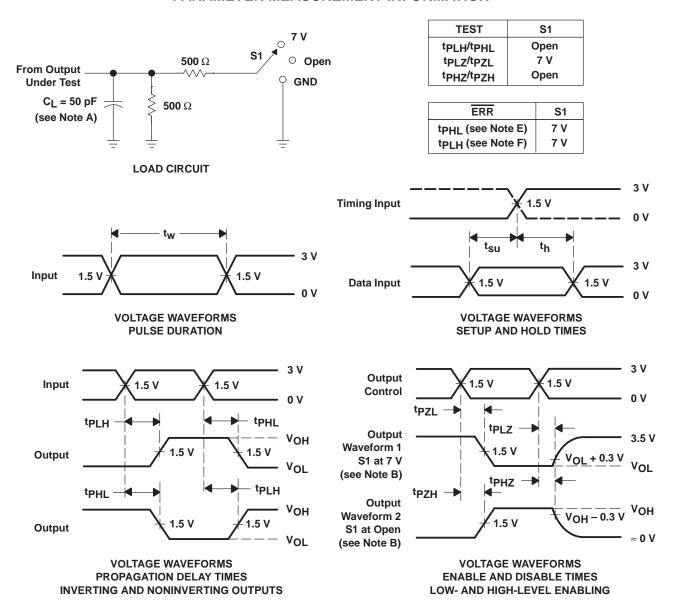
# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> = T <sub>A</sub> = 2	: 5 V, 25°C	SN54AB	Г16833	SN74AB1	Г16833	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>W</sub>	Pulse duration, CLK high or low		3		3,		3		ns
		A port	4.5		4.5	3	4.5		
t <sub>su</sub>	Setup time before CLK↑	CLR	1		813	4	1		ns
		OEA	5		5		5		
t <sub>h</sub>	Hold time after CLK↑	A port or OEA	0		0		0		ns

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TO $V_{CC} = 5 \text{ V},$ $T_{A} = 25^{\circ}\text{C}$			SN54ABT16833		SN74ABT16833		UNIT
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns
t <sub>PHL</sub>	AUIB	BULA	2	3.1	3.9	2	4.5	2	4.3	115
<sup>t</sup> PZH	ŌĒ	A or B	2	3.9	4.9	2	5.8	2	5.6	ns
<sup>t</sup> PZL	OE	AUIB	2.5	4.3	5.1	2.5	6.2	2.5	6	115
<sup>t</sup> PHZ	ŌĒ	A or B	2	3.6	4.5	2	5.5	2	5.4	ns
t <sub>PLZ</sub>	OE	AUB	1.5	3	3.8	1.5	4.7	1.5	4.3	
<sup>t</sup> PLH	A or OE	PARITY	2	4.6	5.4	2/	7	2	6.7	ns
<sup>t</sup> PHL	A or OE	FARITI	2	4.3	5.1	2	6.5	2	6.1	1115
<sup>t</sup> PZH	ŌĒ	PARITY	2	3.6	5	2	5.8	2	5.7	nc
t <sub>PZL</sub>	OE	FARITI	2.5	4.4	5.8	2.5	6.7	2.5	6.5	ns
<sup>t</sup> PHZ	ŌĒ	PARITY	1.5	3.2	4	1.5	4.8	1.5	4.7	20
<sup>t</sup> PLZ	OE	FANIT	1.5	2.9	3.7	1.5	4.2	1.5	4.1	ns
t <sub>PLH</sub>	CLK, CLR	ERR	2	3.4	4.2	2	4.8	2	4.6	ne
<sup>t</sup> PHL	CLK	EKK	2	2.8	3.6	2	4.1	2	3.9	ns

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpHL is measured at 1.5 V.
- F. tpLH is measured at Vol + 0.3 V.

Figure 1. Load Circuit and Voltage Waveforms





#### PACKAGE OPTION ADDENDUM

5-Sep-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ABT16833DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16833DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16833DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16833DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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